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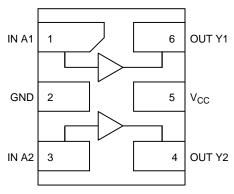
Dual Buffer

The NLX2G16 MiniGate[™] is an advanced high–speed CMOS dual non–inverting buffer in ultra–small footprint.

The NLX2G16 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 1.8 \text{ ns} (Typ) @ V_{CC} = 5.0 \text{ V}$
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Low Power Dissipation: $I_{CC} = 1 \ \mu A$ (Max) at $T_A = 25^{\circ}C$
- 24 mA Balanced Output Source and Sink Capability
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant





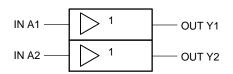
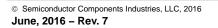


Figure 2. Logic Symbol

PIN ASSIGNMENT

FUNCTIO	N TABLE
Α	Y
L	L

	1 11 17	OUIOIIIIEIII
	1	IN A1
	2	GND
ABLE	3	IN A2
Y	4	OUT Y2
L	5	V _{CC}
Н	6	OUT Y1

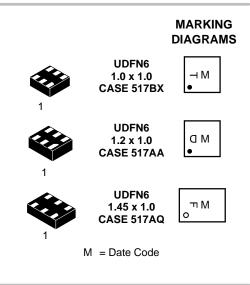


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ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parame	Value	Unit	
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage		-0.5 to +7.0	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-50	mA
Ι _Ο	DC Output Source/Sink Current	±50	mA	
I _{CC}	DC Supply Current Per Supply Pin	±100	mA	
I _{GND}	DC Ground Current per Ground Pin	±100	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
ΤL	Lead Temperature, 1 mm from Case for 10 S	Seconds	260	°C
Τ _J	Junction Temperature Under Bias	150	°C	
MSL	Moisture Sensitivity	Level 1		
F _R	Flammability Rating Oxygen	UL 94 V–0 @ 0.125 in		
ILATCHUP	Latchup Performance Above V_{CC} and Below	±500	mA	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

Tested to EIA/JESD22–A114–A.
Tested to EIA/UESD22–A115–A.

4. Tested to JESD22-C101-A.

5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V _{IN}	Digital Input Voltage	0	5.5	V
V _{OUT}	Output Voltage	0	5.5	V
T _A	Operating Free–Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $\begin{array}{c} V_{CC} = 1.8 \ \forall \pm 0.18 \\ V_{CC} = 2.5 \ \forall \pm 0.2 \ \lor \\ V_{CC} = 3.3 \ \forall \pm 0.3 \ \lor \\ V_{CC} = 5.0 \ \forall \pm 0.5 \ \lor \end{array}$	0 0 0 0	20 20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

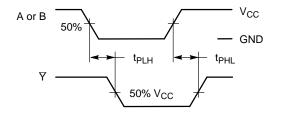
				V_{CC} $T_A = 25^{\circ}C$		T _A = +85°C		T _A = −55°C to +125°C			
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Low-Level Input Voltage		1.65–1.95	0.75 x V _{CC}			0.75 x V _{CC}		0.75 x V _{CC}		V
	vollage		2.3 to 5.5	0.70 x V _{CC}			0.70 x V _{CC}		0.70 x V _{CC}		
V _{IL}	Low-Level		1.65–1.95			0.25 x V _{CC}		0.25 x V _{CC}		0.25 x V _{CC}	V
	Voltage		2.3 – 5.5			0.30 x V _{CC}		0.30 x V _{CC}		0.30 x V _{CC}	
V _{OH}	High– Level Output	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -100 \ \mu \text{A}$	1.65 – 5.5	V _{CC} – 0.1	V _{CC}		V _{CC} – 0.1		V _{CC} – 0.1		V
	Voltage	$\begin{array}{c} V_{IN} = V_{IH} \text{ or } V_{IL} \\ I_{OH} = -4 \text{ mA} \\ I_{OH} = -8 \text{ mA} \\ I_{OH} = -16 \text{ mA} \\ I_{OH} = -24 \text{ mA} \\ I_{OH} = -32 \text{ mA} \end{array}$	1.65 2.3 3.0 3.0 4.5	1.29 1.9 2.4 2.3 3.8	1.52 2.15 2.8 2.68 4.2		1.29 1.9 2.4 2.3 3.8		1.29 1.9 2.4 2.3 3.8		
V _{OL}	Low–Level Output	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 100 \ \mu A$	1.65 – 5.5			0.1		0.1		0.1	V
	Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$ $I_{OL} = 16 \text{ mA}$ $I_{OL} = 24 \text{ mA}$ $I_{OL} = 32 \text{ mA}$	1.65 2.3 3.0 3.0 4.5		0.08 0.1 0.15 0.22 0.22	0.24 0.3 0.4 0.55 0.55		0.24 0.3 0.4 0.55 0.55		0.24 0.3 0.4 0.55 0.55	
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I _{OFF}	Power–Off Output Leakage Current	V _{IN} or V _{OUT} = 5.5 V	0			1.0		10		10	μΑ
I _{CC}	Quiescent Supply Current	$V_{IN} = 0 V \text{ or } V_{CC}$	5.5			1.0		10		10	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

		V _{CC} Test		T _A = 25°C			T _A = −55°C to +125°C			
Symbol	Parameter	(V)	Condition	Min	Тур	Мах	Min	Max	Unit	
t _{PLH} , t _{PHL}	Propagation Delay Input A to Output	1.65–1.95	$R_L = 1 M\Omega,$ $C_L = 15 pF$	1.8	8.0	9.6	1.8	10.2	ns	
		2.3–2.7	R _L = 1 MΩ, C _L = 15 pF	1.0	3.0	5.2	1.0	5.8		
		3.0–3.6	R _L = 1 MΩ, C _L = 15 pF	0.8	2.3	3.6	0.8	4.0		
			R _L = 500 Ω, C _L = 50 pF	1.2	3.0	4.6	1.2	5.1		
		4.5–5.5	R _L = 1 MΩ, C _L = 15 pF	0.5	1.8	2.9	0.5	3.2		
			R _L = 500 Ω, C _L = 50 pF	0.8	2.4	3.8	0.8	4.2		
C _{IN}	Input Capacitance	5.5	$V_{IN} = 0 V \text{ or } V_{CC}$		7.0				pF	
C _{PD}	Power Dissipation Capacitance (Note 6)	3.3 5.5	$\begin{array}{c} 10 \text{ MHz} \\ \text{V}_{\text{IN}} = 0 \text{ V or } \text{V}_{\text{CC}} \end{array}$		9 11				pF	

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ nS}$)

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption: P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.



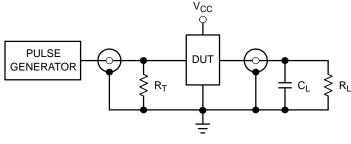


Figure 3. Switching Waveforms

 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

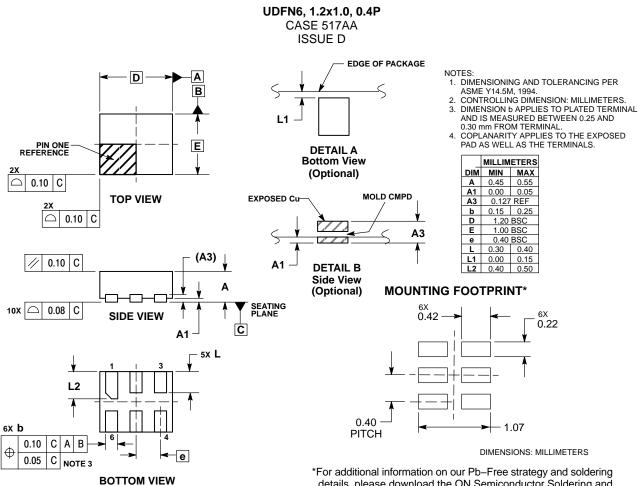
ORDERING INFORMATION

Device	Package	Shipping [†]
NLX2G16MUTCG	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G16AMUTCG, NLVX2G16AMUTCG*	UDFN6, 1.45 x 1.0, 0.5P (Pb–Free)	3000 / Tape & Reel
NLX2G16CMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

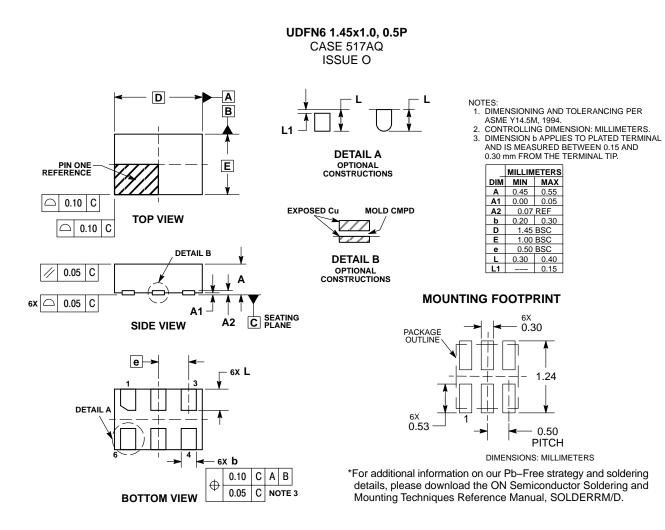
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable.

PACKAGE DIMENSIONS



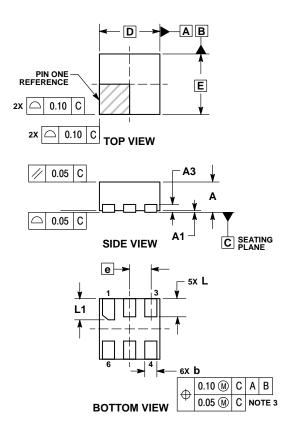
details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS



PACKAGE DIMENSIONS

UDFN6 1.0x1.0, 0.35P CASE 517BX ISSUE O

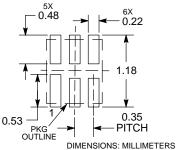


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP. 4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

BUI	BURRS AND MOLD FL				
		MILLIMETERS			
DI	М	MIN	MAX		
A		0.45	0.55		
A	1	0.00	0.05		
Α	3	0.13 REF			
b		0.12	0.22		
D)	1.00	BSC		
E		1.00	BSC		
е		0.35	BSC		
L		0.25	0.35		
L	1	0.30	0.40		

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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